



International Workshop on



Advanced Patterning Solutions

The 9th International Workshop on Advanced Patterning Solutions

第九届国际先进光刻技术研讨会

October 14-15, 2025, WuZhou Hotel, Shenzhen, Guangdong Province, China

2025 年 10 月 14 日至 15 日，五洲宾馆五洲厅，广东深圳，中国

(October 13 for registration, 10 月 13 日注册)

Agenda 会议日程

Program Chairs: Qiang Wu, Shiyuan Liu

Registration 注册		
13 Oct. 2025	10:30-20:00	酒店大厅 WuZhou Hotel
14-15 Oct. 2025	08:00-18:00	五洲厅 Wuzhou Banquet Hall
DAY 1:		
14 Oct. 2025 (Tuesday)		
Wuzhou Banquet Hall 五洲厅		
DAY 1-Morning		
08:30-09:00	Opening Ceremony & Welcome Address Chair: Yayi Wei	
Welcome Address	Conference Chairs Address Host/Organizer Address	
09:00-10:10	Plenary Session I Chair: Shiyuan Liu	
	<i>5 minutes Q&A for each talk</i>	
09:00-09:35	Linyong(Leo) Pang (D2S, Inc): (KEYNOTE) The Most Effective Way to Advance Technology Nodes – Even Mature Ones: Production-Ready Full-Chip Curvilinear ILT and Curvilinear Masks for DUV	
09:35-10:10	Qiang Wu (Fudan University): (KEYNOTE) DICO in Times of Large Scale Process, Equipment, and Material Development	
10:10-10:40	Group Photo & Coffee Break	
10:40-11:50	Plenary Session II Chair: Qiang Wu	

	<i>5 minutes Q&A for each talk</i>
10:40-11:15	Bei Yu (The Chinese University of Hong Kong): (KEYNOTE) Large Scale VLSI Mask Optimization
11:15-11:50	ByoungHo Lee (Hitachi High-tech Corporation): (KEYNOTE) The Role and Direction of MI in the Era of 3D
11:50-12:20	Poster Session Authors should be present at your poster.
12:20-13:50	Lunch
DAY 1-Afternoon	
13:50-15:30	Patterning Session Chairs: Wenzhan Zhou & Jin Li
	<i>5 minutes Q&A for each talk</i>
13:50-14:15	Jette van den Broeke (ASML): (INVITED) Printing towards the resolution limit of DUV immersion lithography
14:15-14:40	Ingo Bork (Siemens): (INVITED) Practical solutions for writing curvilinear shapes on photomasks
14:40-15:05	Chin-Chou Kevin Huang (KLA): (INVITED) From Metrology to Control: A Comprehensive Overlay Solution for IC Manufacturing and Packaging Challenges
15:05-15:30	Lei Zhu (Wintech-Nano Co., Ltd.): (INVITED) Application of failure analytical techniques for photoresist and photomask defects
15:30-15:50	Coffee Break
15:50-17:25	AI and Process Session Chairs: Weimin Gao & Liguozhang
	<i>5 minutes Q&A for each talk</i>
15:50-16:15	Yelin Hu (Engitist Corporation): (INVITED) Machine Learning and Artificial Intelligence in Semiconductor Metrology and Inspection for Smart Manufacturing
16:15-16:40	Ao Chen (SEIDA Technology Co. Ltd.): (INVITED) AI Assisted Etch Models
16:40-17:05	Xianhe Liu (Fudan University): (INVITED) Study of SMO for High-NA EUV Lithography via Sub-2 nm Nodes
17:05-17:25	Devin Sima (Fujian Jinhua Integrated Circuit Co., Ltd.): A composite model for LELE process

19:00-19:05	Best Poster Award 最佳墙报颁奖 Wuzhou Banquet Hall 五洲厅
19:05-21:00	Welcome Banquet for all attendees 晚宴 (Wuzhou Banquet Hall 五洲厅)

Day 2:	
15 Oct. 2025 (Wednesday) — Parallel Session I, 并行报告会场 I	
Wuzhou Banquet Hall Part I, 五洲厅 (一)	
DAY 2–Morning	
08:30-10:05	Mask Equipment Session Chairs: Jiangliu Shi & Modern Xu
	<i>5 minutes Q&A for each talk</i>
08:30-08:55	Robert Eklund (Mycronic AB): (INVITED) The Laser mask writer and its unique position in the semicon industry
08:55-09:20	Sebastian Vollmar (Carl Zeiss SMT): (INVITED) Advancing E-Beam Repair: Unveiling the MeRiT® MG neo's Enhanced Throughput and Expanded Capabilities
09:20-09:45	Ya Xu (SUSS MicroTec (Shanghai) Co., Ltd): (INVITED) Development of Sulfate and Ammonium Free Resist Stripping and Final Cleaning Process
09:45-10:05	Weiyu Xu (Carl Zeiss SMT): Mask yield accelerator: AIMS AutoAnalysis application to high volume manufacturing
10:05-10:30	Coffee Break
10:30-12:20	Mask Optimization Session Chairs: Yijiang Shen & Haizhou Yin
	<i>5 minutes Q&A for each talk</i>
10:30-10:55	Haizhou Yin (Siemens): (INVITED) Accelerating Semiconductor Innovation: ML/AI Solutions for Mask Synthesis and Beyond
10:55-11:20	Jichuan Xiong (Nanjing University of Science and Technology): (INVITED) Phase-Space-Driven ILT with Swin Transformers: A Generative AI Framework for Sub-Wavelength Mask Optimization
11:20-11:40	Juan Wei (Beijing Superstring Academy of Memory Technology): Enhancing ILT Modeling Efficiency: Symmetry-Averaged Gauge Processing and Kernel DDM for RMS and Runtime Optimization
11:40-12:00	Yuhang Wang (Guangdong University of Technology): Parametric Curvilinear OPC Using B-splines Data Format
12:00-12:20	Shi Chen (Fudan University): M3D Effect Compensation in 2 nm Node EUV Lithography via

	Controlled Aberration Manipulation
12:20-13:50	Lunch
DAY 2-Afternoon	
13:50-15:25	Equipment Session Chairs: Yun Zhan & Jing Li
	<i>5 minutes Q&A for each talk</i>
13:50-14:15	Yoshiaki Yamada (Hangzhou Cobetter Filtration Equipment Co. Ltd.): (INVITED) Next-Generation Polyethylene Membrane with Ultra-Fine Pores Beyond Sub-1nm for Lithography Chemical Filtration
14:15-14:40	Jie Liu (ASML Cymer): (INVITED) Maximizing System Performance to Improve Process, Availability and Sustainability
14:40-15:05	Yang Liu (HIT): (INVITED) Modeling and Control of Linear Reluctance Actuators for Next-Generation Wafer Scanners
15:05-15:45	Coffee Break
15:45-17:15	Other Lithography Session Chairs: Shisheng Xiong & Yang Liu
	<i>5 minutes Q&A for each talk</i>
15:45-16:10	Qiming Zhang (University of Shanghai for Science and Technology): (INVITED) Artificial neural networks enabled by direct laser writing
16:10-16:35	Xing Cheng (Southern University of Science and Technology): (INVITED) Opportunities and Perspectives of Nanoimprint for Commercial Microelectronic Manufacturing
16:35-16:55	Chenhui Deng (Institute of Electrical Engineering, CAS): High-speed versatile pattern generator for high-resolution electron-beam lithography
16:55-17:15	Xin Zhuang (Southern University of Science and Technology): Scanning Helium Ion Beam Lithography on Freestanding Silicon Nitride Membranes for Sub-Nanometer Resist Characterization
17:15-17:20	Closing Plenary Address 闭幕致辞 Chairs: Qiang Wu, Shiyuan Liu & Yayi Wei

Day 2:

15 Oct. 2025 (Wednesday) — Parallel Session II, 并行报告会场 II
Wuzhou Banquet Hall Part II, 五洲厅（二）

DAY 2-Morning	
08:30-09:55	Computational Lithography Session Chairs: Xu Ma & Xiaodong Meng
	<i>5 minutes Q&A for each talk</i>
08:30-08:55	David H. Wei (Guangdong University of Technology): (INVITED) Computational Imaging and Computational Lithography
08:55-09:15	Cai Chen (Advanced Manufacturing EDA Co., Ltd.): Enhancing Lithographic Resolution for Via and Metal Layers in Advanced Semiconductor Manufacturing: NTD-Based Multi-Patterning Strategies
09:15-09:35	Yuhao Wang (Hangzhou HFC Semiconductor Corp): D-CAF: Data-Driven CPU Allocation Framework for Efficient OPC Workloads
09:35-09:55	Chuansheng Dai (Advanced Manufacturing EDA Co., Ltd): 3D resist profile simulation for compact modeling considering z-diffusion
09:55-10:35	Coffee Break
10:35-12:25	Computational Lithography Session II Chairs: David H. Wei & Sikun Li
	<i>5 minutes Q&A for each talk</i>
10:35-11:00	Yanli Li (Fudan University): (INVITED) Imaging Characteristics of Hyper NA (0.75 NA) EUV Lithography in sub-2 nm Logic Technology Nodes
11:00-11:25	Jing Fu (Shanghai Silicon Thread Technology Co., Ltd): (INVITED) AI-Assisted Hotspot-Aware Layout Correction for Lithography-Friendly DTCO
11:25-11:45	Ningmu Zou (Nanjing University): SVD-based Layout Representation for Lithographic Hotspot Detection
11:45-12:05	Kaisheng Chen (Shanghai Optical Lithography Engineering Corp.): Fraunhofer diffraction by rectangular patterns on mask: a generic diffraction formula for modeling perspective
12:05-12:25	Haofeng Guo (Changchun Institute of Optics, Fine Mechanics and Physics, CAS): A low-memory-consumption lithography imaging model based on the Runge-Kutta Iterative Solution (RKIS) method
12:25-13:50	Lunch
DAY 2-Afternoon	
13:50-15:00	X-ray Source and Metrology Session

	Chairs: Qiang Wu & Kan Zhou
	<i>5 minutes Q&A for each talk</i>
13:50-14:15	Lifeng Wang (Institute of Advanced Light Source Facilities): (INVITED) High order harmonic generation in capillary driven by few-cycle laser pulses
14:15-14:40	Guangcai Chang (Institute of High Energy Physics, CAS): (INVITED) Hard X-ray Nanoprobe Beamline of a new synchrotron light source - High Energy Photon Source (HEPS)
14:40-15:00	Shuzhe Cao (Zhejiang University): Coating Defect Localization via Patch-Guided Generative Adversarial Networks
15:00-15:40	Coffee Break
15:40-16:20	Process and Metrology Session Chairs: Weijie Shi & Xianhe Liu
	<i>5 minutes Q&A for each talk</i>
15:40-16:00	Ganlin Song (Beijing Superstring Academy of Memory Technology): Innovative Topographic Mark Generation and Process Optimization for Enhancing Overlay Mark Signal in 3D Structures
16:00-16:20	Zhengpeng Zhang (Fudan University): Optimization of Process Parameters to Reduce Photon Absorption Stochastics for Bidirectional Patterning with EUV Single Exposure
16:20-16:25	Closing Plenary Address 闭幕致辞 Chairs: Qiang Wu, Shiyuan Liu & Yayi Wei

Day 2:	
15 Oct. 2025 (Wednesday) — Parallel Session III, 并行报告会场 III	
Wuzhou Banquet Hall Part III, 五洲厅（三）	
DAY 2-Morning	
08:30-10:00	X-ray Metrology Session Chairs: Feng Luo & Ruzhi Zhang
	<i>5 minutes Q&A for each talk</i>
08:30-08:55	Yasin Ekinci (Paul Scherrer Institute): (INVITED) EUV metrology methods for semiconductor manufacturing applications
08:55-09:20	Jun Zhao (Shanghai Advanced Research Institute): (INVITED) Soft X-ray interference lithography and its applications
09:20-09:40	Jiahao Zhang (Huazhong University of Science and Technology): X-ray critical dimension metrology with optimal experimental design

	using the Fisher information
09:40-10:00	Yuxiang Huang (Shenzhen Angstrom Excellence Technology Co. Ltd): Semiconductor Metrology Tool: X-Ray Diffraction, X-Ray Reflectivity and X-Ray Fluorescence Techniques
10:00-10:20	Coffee Break
10:20-11:50	Photoresist Session I Chairs: Guoqiang Yang & Dean Wu
	<i>5 minutes Q&A for each talk</i>
10:20-10:45	Feng Luo (Nankai University): (INVITED) EUV Photoresist for Advanced 0.55NA Lithography
10:45-11:10	Hideaki Tsubaki (FUJIFILM): (INVITED) Negative-Tone-Imaging (NTI) Process and Material Technology for ArF Immersion and EUV Lithography
11:10-11:30	Ruiwen Ai (Xuzhou B&C Chemical Co.,Ltd): A Feasible Approach to Understand Acid Diffusion in DUV Resist Using Open Frame Exposure
11:30-11:50	Yi-Fan Shen (Suzhou Laboratory): Acid Diffusion Detection in Chemically Amplified Photoresists
12:10-13:50	Lunch
DAY 2-Afternoon	
13:50-15:25	Photoresist Session II Chairs: Mark Neisser & Bing Li
	<i>5 minutes Q&A for each talk</i>
13:50-14:15	Ruzhi Zhang (Suzhou Laboratory): (INVITED) Molecular Feature Influence on ArF Photoresist Polymer Dissolution Behavior
14:15-14:40	Lei Zhang (Nankai University): (INVITED) Molecular Engineering of Metal-Oxo Clusters for Advanced Patterning Applications
14:40-15:05	Yang Hu (Tsing-innovation Semiconductor Company): (INVITED) MOR photoresists: the next generation patterning solutions for Moore's more
15:05-15:25	Zhongmei Han (PiBond Oy): Metal oxides and organometal complexes as alternatives for lithography hard masks
15:25-15:45	Coffee Break
15:45-17:10	Photoresist and Material Session

	Chair: Xudong Guo
	<i>5 minutes Q&A for each talk</i>
15:45-16:10	Yu Chen (Suzhou Rainbowmaterial Co., Ltd.): (INVITED) High etching ration ArF immersion BARC to improve advanced lithographs technology
16:10-16:30	Ruzhi Zhang (Suzhou Laboratory): Development of High-Performance NTD Developers via HSP-Assisted HTE
16:30-16:50	Xiang Dong (Shanghai B&C Chemical Co., Ltd.): Application and Advantage of RAFT Polymerization in High-resolution Lithography Formulation
16:50-17:10	Jialin Wu (Fudan University): A Hierarchical Pipeline for Data-Efficient χ Prediction in Block Copolymers via Large Language Models
17:10-17:15	Closing Plenary Address 闭幕致辞 Chairs: Qiang Wu, Shiyuan Liu & Yayi Wei

Agenda is subject to change

Poster Session

14 Oct. 2025

11:50-12:20 Outdoor of Wuzhou Banquet Hall 五洲厅前廊

IWAPS2025-P-01	Kang Wang*, ZhaoLong Luo, Shiqi Yin (Nexchip Semiconductor Corporation) Full-Field Contour-Based PWA Enables Precision Depth-of-Focus Characterization at Advanced-Node
IWAPS2025-P-02	Kang Wang*, Zhaolong Luo, Die Liu (Nexchip Semiconductor Corporation) Smart RBAF: Hierarchical Main Pattern Definition for Advanced-Node Lithography Enhancement
IWAPS2025-P-03	Tong Liang, Jing Li* (Zhejiang University) A measurement scheme for beam parallelism based on image measurement method
IWAPS2025-P-05	Caiwei Shang¹, Jiacheng Luo¹, Weixuan Zeng², Yan Zhang², Shisheng Xiong^{1,2,*} (1 Fudan University; 2 Zhangjiang Laboratory) Fast Simulation of Directed Self-Assembly for Contact Hole Multiplication with an Optimized Compact Model
IWAPS2025-P-06	Xin Zhou¹, Yuejing Qi^{1,2,*}, Zhipeng Wu^{1,2}, Wei Qi^{1,2} (1 Institute of Microelectronics of the Chinese Academy of Sciences; 2 University of Chinese Academy of Sciences) A Moving-average-filter-based Dynamic Decoupling Control for Wafer Stage Motion Systems
IWAPS2025-P-07	Yanbei Nan, Zhenkun Zhang, Yanqiu Li* (Beijing Institute of Technology) Design of an anamorphic extreme ultraviolet lithography projection objective adopted high order XY polynomial freeform surfaces
IWAPS2025-P-08	Weichen Huang, Yangqiu Li* (Beijing Institute of Technology) High-fidelity curvilinear SRAF method adopting distance-versus-angle-signature
IWAPS2025-P-09	Zhenkun Zhang, Yanbei Nan, Yanqiu Li* (Beijing Institute of Technology) Wavefront Fitting of Different Obscuration Shapes in Anamorphic Extreme Ultraviolet Lithography Projection Objective
IWAPS2025-P-10	Zhilong Zhong¹, Yunhao Liu¹, Jiamin Liu^{1,*}, Pinxuan He¹, Hao Jiang¹, Honggang Gu¹, Shiyuan Liu^{1,2,*} (1 Huazhong University of Science and Technology; 2 Optics Valley Laboratory) Full-chip EUVL simulation based on wide-angle full-vector beam propagation method
IWAPS2025-P-11	CHIH-LI(Julius) Chen¹, Zekui Li¹, Alex Fan³, Dawen Yang³, Pinhong Lin³, Lei Chen³, Xiaodong Meng^{2,3,*} (1 Rong Semiconductor Co., Ltd.; 2 Tsinghua University; 3Advanced Manufacturing EDA Co., Ltd.) An effective methodology to accelerate early stage of OPC development by use of TVeXpert and CPG

IWAPS2025-P-12	Benjamin Shen* , Wenchun Huang, Chunhung Wu (Advanced Manufacturing EDA Co., Ltd.) OPC Consistency Improvement with Hash Code
IWAPS2025-P-13	Qinghua Ye^{1,2}, Dongchao Pan², Chun Zhang², Diyu Fu, Sikun Li^{1,2,*} (1 Shanghai University; 2 Shanghai Institute of Optics and Fine Mechanics, Chinese Academy of Sciences) Real-time Shack-Hartmann Wavefront Processor with FPGA Acceleration
IWAPS2025-P-14	Chaoxin Feng¹, Cheng Qian², Ruoran Jia^{3,*} (1 University of Chinese Academy of Sciences; 2 University of Science and Technology of China; 3 Chongqing Institute of Green and Intelligent Technology, Chinese Academy of Sciences) An effective mask optimization method using Deep Reinforcement Learning
IWAPS2025-P-16	Pinxuan He¹, Jiamin Liu^{1,*}, Jinlong Zhu¹, Honggang Gu¹, Hao Jiang¹, Shiyuan Liu^{1,2,*} (1 Huazhong University of Science and Technology; 2 Optics Valley Laboratory) Large-scale electromagnetic simulations enabled by the modified Born series with virtual absorbing boundaries
IWAPS2025-P-17	Yingxiong Guo¹, Wenzhang Li¹, T. H. Ying¹, Devin Sima¹, Siqi Wang², Shengrui Zhang², C. M. Hu^{1,*} (1 Fujian Jinhua Integrated Circuit Co., Ltd.; 2 Dongfang Jingyuan Electron Co., Ltd.) A Comprehensive intra-CD uniformity control through optimizing pattern loading effect correction by AI-trained model
IWAPS2025-P-18	Tatsi IAO¹, Fengnien Tsai¹, T.H.Ying¹, Shengrui.Zhang², C.M. Hu^{1,*} (1 Fujian Jinhua Integrated Circuit Co., Ltd.; 2 Dongfang Jingyuan Electron Co., Ltd.) A Co-optimization Flow to Expanding PWQ through HSF and Model-based loading effect for DRAM LELE Metal Layer
IWAPS2025-P-19	Yanting Xu¹, Jiacheng Luo², Zhiyong Wu¹, Wenda Bao¹, Yudan Su¹, Yan Zhang¹, Shisheng Xiong^{1,2,*} (1 Zhangjiang laboratory; 2 Fudan University) Quantitative Characterization of Brushes Grafting for Graphoepitaxial Directed Self-assembly
IWAPS2025-P-20	Yanzhong Ma* , Xiangyu Ma*, Langfeng Wen (Skyverse Tech. Co. Ltd.) Synalib: A fast OCD engine with parametric process flow modeling for high-throughput semiconductor metrology
IWAPS2025-P-21	Haoyang Liang¹, Honggang Gu^{1,2,*}, Shiyuan Liu^{1,2,*} (1 Huazhong University of Science and Technology; 2 Optics Valley Laboratory) Sub-wavelength scale lithographic defect detection based on vortex light
IWAPS2025-P-22	Zhiyong Wu¹, Qingshu Dong², Huangyan Shen², Shengru Niu², Yan Zhang¹, Fei Pei¹, Weixuan Zeng¹, Zhonghan Cao¹, Mingkun Zhao¹, Zili Li^{1,2}, Weihua Li², Shisheng Xiong^{1,2,*} (1 Zhangjiang Laboratory; 2 Fudan University;)

	Simultaneous Generation of Contact Holes with Circular and Rectangular Shapes through Graphoepitaxy Directed Self-Assembly of Block Copolymer/Homopolymer Blends
IWAPS2025-P-23	Hui Zeng^{1*}, Libin Zhang², Zhicheng Liu¹, Zhenguo Tian², Guiqi Li¹, Fangyi Shi¹, Zhuohong Zhou¹, Miaohua Zhang¹, Xing Yang³ (¹ CanSemi Technology Inc., ² Institute of Microelectronics, ³ Nanjing Chengxin Integrated Circuit Technology Research Institute Co., Ltd.) Critical Dimension Measurement Method for Curvilinear Patterns and Application in Lithography Process Development for Silicon Photonics Platform
IWAPS2025-P-24	Chenpeng Zhao, Jazlyn Zhang, Pei Xie, Can Duan (Semiconductor Technology Innovation Center (STIC)) Optical Diameter-Driven Optimization of Optical Proximity Correction (OPC) Model Fidelity and Computational Efficiency
IWAPS2025-P-25	Di Liang, Miao Jiang, Yaokun Li, Yuxing Zhou, Jiahao Xi, Enqiang Tian, Mingyi Yao, Ganlin Song, Jiangliu Shi, Guowei Jiang* (Beijing Superstring Academy of Memory Technology) An Open KLayout-Python-Based Framework for Automated AIM Overlay Mark Generation
IWAPS2025-P-27	Sicong Wang¹, Xiaoqi Pang², Pei Yu², Chao Shang², Zhiwei Wang³, Xianhui Chen³, Bowen Chen⁴, Yi Yin⁴, Xia Chen⁵, Jie Zhang⁵, Trina Wong², Feng Hong², Athena Chang² (¹ Huazhong University of Science and Technology; ² Shenzhen Angstrom Excellence Technology Co. Ltd.; ³ University of Science and Technology of China; ⁴ Zhejiang University; ⁵ Shenzhen Institute of Advanced Technology, Chinese Academy of Sciences) Thin Film Metrology Techniques: X-Ray Diffraction and X-Ray Reflectivity
IWAPS2025-P-28	Chao Liu, Jing Li (Zhejiang University) Polarization-Induced Angular Deviation and Spatial Centroid Jumps in Laser Beams
IWAPS2025-P-30	Jinyuan Song, Jing Li*, Qingyang Zhang (Zhejiang University) Apparatus and Method for Testing the Optical Uniformity of Optical Crystals
IWAPS2025-P-31	Jingyu Huang^{1,2}, Bohua Yin^{1,2}, Zhengjie Li^{1,2}, Botong Sun^{1,2}, Pengfei Wang^{1,2}, Li Han^{1,2}, Liping Zhang³ (¹ Institute of Electrical Engineering Chinese Academy of Sciences; ² University of Chinese Academy of Sciences; ³ Beijing Academy of Quantum Information Sciences) Process Window and Resolution Limit Investigation of PMMA Resist under 30 kV Electron Beam Lithography
IWAPS2025-P-32	Jiakun Lan¹, Jibin He¹, Xue Zhou¹, Yanan Bao^{1,2}, Guodong Zhou^{1,*} (¹ Zhejiang University; ² Zhejiang ICsprout Semiconductor Co., Ltd.)

	A Swing Curve Fitting Algorithm Based on Physics-Informed Neural Networks
IWAPS2025-P-33	Xue Zhou¹, Tianhao Huang¹, Jiakun Lan¹, Jianming Wu², Yanan Bao^{1,2}, Guodong Zhou^{1,*} (¹ Zhejiang University; ² Zhejiang ICsprout Semiconductor Co., Ltd.) A Process-Parameter-driven Cross-Attention Convolutional Autoencoder for High-Precision Critical Dimension Prediction
IWAPS2025-P-38	Jun-Dan Huang, Ming-Qiang Zhu (Huazhong University of Science and Technology) Photoacid-induced crosslinking/degradation of poly (2,3-dihydrofuran) for multi-tone photolithography
IWAPS2025-P-39	Xiao Tan¹, Jun-dan Huang¹, Ming-Qiang Zhu^{1,*} (Huazhong University of Science and Technology) Etch-Resistant Chemically Amplified Positive-Tone Photoresist with Synergistic Dual Nonionic Photoacid Generators
IWAPS2025-P-40	Ying-Yi Ren¹, Cong Li¹, Shi-li Xiang², Ming-Qiang Zhu^{1,*} (Huazhong University of Science and Technology) Photoswitchable Branched Polyurethanes Based on Hexaarylbiimidazole for Photolithography

Agenda is subject to change

For update agenda and further information, please visit the website: www.iwaps.org